#### 507381001 07/12/2022

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
JANAK PATEL	06/23/2021
RICHARD GRAF	06/24/2021
MANISH NAYINI	06/23/2021
NAZMUL HABIB	06/21/2021

### **RECEIVING PARTY DATA**

Name:	MARVELL SEMICONDUCTOR, INC.	
Street Address:	5488 MARVELL LANE	
City:	SANTA CLARA	
State/Country:	CALIFORNIA	
Postal Code:	95054	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	17360571	

### CORRESPONDENCE DATA

Fax Number: (408)222-2755

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408-222-2500 Email: sherir@marvell.com

**Correspondent Name: KELVIN VIVIAN** 

Address Line 1: 5488 MARVELL LANE

Address Line 4: SANTA CLARA, CALIFORNIA 95054

ATTORNEY DOCKET NUMBER:	MP13295	
NAME OF SUBMITTER: KELVIN VIVIAN		
SIGNATURE:	/Kelvin Vivian/	
DATE SIGNED:	07/12/2022	

### **Total Attachments: 8**

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Docket#: MP13295

#### ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency for which is hereby acknowledged, I or We, the undersigned,

# Janak Patel, Richard Graf, Manish Nayini, Nazmul Habib

who have created certain invention for which one or more patent applications identified below (hereinafter "the Patent Application(s)") that have been, or are to be filed:

Marvell Case No.	Application No.	Filing Date	<u>Title</u>
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MP13295	US 17/360,571	06/28/2021	Heat Sink Configuration for Multi- Chip Module
MP13295WO	PCT/US21/39429	06/28/2021	Heat Sink Configuration for Multi- Chip Module

Do hereby confirm any prior assignment, and to the extent that I have not already done so, agree to sell, assign, and transfer, and do hereby sell, assign and transfer to Marvell Semiconductor, Inc., a corporation of California, having a place of business at 5488 Marvell Lane, Santa Clara, CA 95054, and its successors or assigns (hereinafter "Assignee"), the entire rights, title, and interest, including all priority rights, in or to any and all inventions described in the Patent Application(s), the Patent Application(s), and all continuations in whole or in part, divisions, and other applications claiming priority directly or indirectly from the Patent Application(s) which have been or are to be filed in the United States and/or any foreign countries including national stage applications, and any patents, including utility models and other similar registrations, in the United States and/or any foreign countries which may be granted thereon, including but not limited to reissues, renewals, and reexaminations thereof;

Authorize and request that the attorneys of record in any of the Patent Application(s) insert in this assignment the filing date(s) and application number(s) of the Patent Application(s) when officially known (the Assignee authorizes and requests the same);

Agree that Assignee may apply for and receive patents including utility models and other similar registrations for the foregoing rights, title and interest in its own name, in the United States and/or any foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of the Assignee, and its successors or assigns, the undersigned will execute all rightful oaths, declarations, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to the Assignee, and its successors or assigns all facts known to the undersigned relating to the foregoing rights, title and interest; and generally do everything possible and reasonable which the Assignee, and its successors, or assigns consider necessary, desirable or expedient for aiding in securing, maintaining and enforcing proper protection for applicable patent rights and for vesting applicable title in the Assignee and its successors or assigns; and

Covenant with the Assignee, and its successors or assigns that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to

others by the undersigned, there are no outstanding encumbrances, liens or other obligations or restrictions on the rights, titles and interests herein assigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set my signature or our signatures on the date indicated below.

Full Name of First Inventor:	
Janak Patel	
Inventor's Signature:	Date: Month/Day/Year
/Janak Patel/	6/23/2021
Full Name of Second Inventor:	
Richard Graf	
Inventor's Signature:	Date: Month/Day/Year
Full Name of Third Inventor:	
Manish Nayini	
Inventor's Signature:	Date: Month/Day/Year
Full Name of Fourth Inventor:	
Nazmul Habib	
Inventor's Signature:	Date: Month/Day/Year
Accepted by:	
MARVELL SEMICONDUCTOR, INC.	
By: Letz Ve	<u> </u>
Name: Kelvin M. Vivian	<u> </u>
Title: Director, Assistant General Counsel, IP Developm	<u>nent</u>
<b>Date:</b> 24 June 2021	

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Inventor's Signature:	Date: Month/Day/Year
Full Name of Second Inventor:	
Richard Graf	
Inventor's Signature:	Date: Month/Day/Year
/Richard Graf/	06/24/2021
Full Name of Third Inventor:	
Manish Nayini	
Inventor's Signature:	Date: Month/Day/Year
Full Name of Fourth Inventor:	
Nazmul Habib	
Inventor's Signature:	Date: Month/Day/Year
Accepted by:	
MARVELL SEMICONDUCTOR, INC.	
By: Jel-Ale	
Name: Kelvin M. Vivian	<del></del>
Title: Director, Assistant General Counsel, IP Development	<u>nent</u>
Date: 24 June 2021	<u></u>

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Manish Nayini	
Inventor's Signature:	Date: 06/23/2021
Full Name of Fourth Inventor:	
Nazmul Habib	
Inventor's Signature:	Date: Month/Day/Year
Accepted by:	
MARVELL SEMICONDUCTOR, INC.	
By: Jela V	
Name: <u>Kelvin M. Vivian</u>	
Title: Director, Assistant General Counsel, IP Developm	<u>nent</u>
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